



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





Surface Mount Gaskets and Grounding Pads

Our SMG gaskets can be used with many different types of board level shielding needs and when grounding points are required on your board. Form-in-Place gaskets can be eliminated by transferring the gasket to the board rather than to the thin edge of a casting or machined housing. No fear of damaging a thin Form-in-Place gasket during handling and assembly process. High speed SMT assembly of our tape and reel supplied gaskets make this a low cost reliable assembly option.

Part Numbers	Sizes						Packaging (parts per reel)	Core Materials	Cross Section (not to scale)
	Height	Width		Length					
SMG098118R-0.098	0.098	2.5	0.118	3	0.098	2.5	2100	Hollow High Temp. Sil. Sponge	
SMG118118R-0.079	0.118	3	0.118	3	0.079	2	1800	Hollow High Temp. Sil. Sponge	
SMG118118R-0.118	0.118	3	0.118	3	0.118	3	1800	Solid High Temp. Foam	
SMG118157R-0.197	0.118	3	0.157	4	0.197	5	1800	Hollow High Temp. Sil. Sponge	
SMG118197R-0.256	0.118	3	0.197	5	0.256	7	1500	Solid High Temp. Foam	
SMG256197R-0.118	0.256	6.5	0.197	5	0.118	3	1100	Solid High Temp. Foam	
SMG157256R-0.276	0.157	4	0.256	6.5	0.276	7	1200	Hollow High Temp. Sil. Sponge	
SMG236295R-0.157	0.236	6	0.295	7.5	0.157	4	1200	Hollow High Temp. Sil. Sponge	
SMG236354R-0.315	0.236	6	0.354	9	0.315	8	600	Hollow High Temp. Sil. Sponge	
SMG295197R-0.138	0.295	7.5	0.197	5	0.138	3.5	1000	Hollow High Temp. Sil. Sponge	

Black = inches Blue = mm Tolerance: +/- .019" (.48mm)

Applications

- Mobile Electronics
- Computers
- Integrated Circuits

Benefits

- Low Cost
- Suitable for Automated Placement
- Tape & Reel Packaging
- Off-The-Shelf
- Reflow Capabilities
- Low Compression Requirements
- Resilient

Material

- Outer Wrap
- Polyimide coated Sn/Cu



**SURFACE
MOUNT GASKETS**

www.LeaderTechInc.com

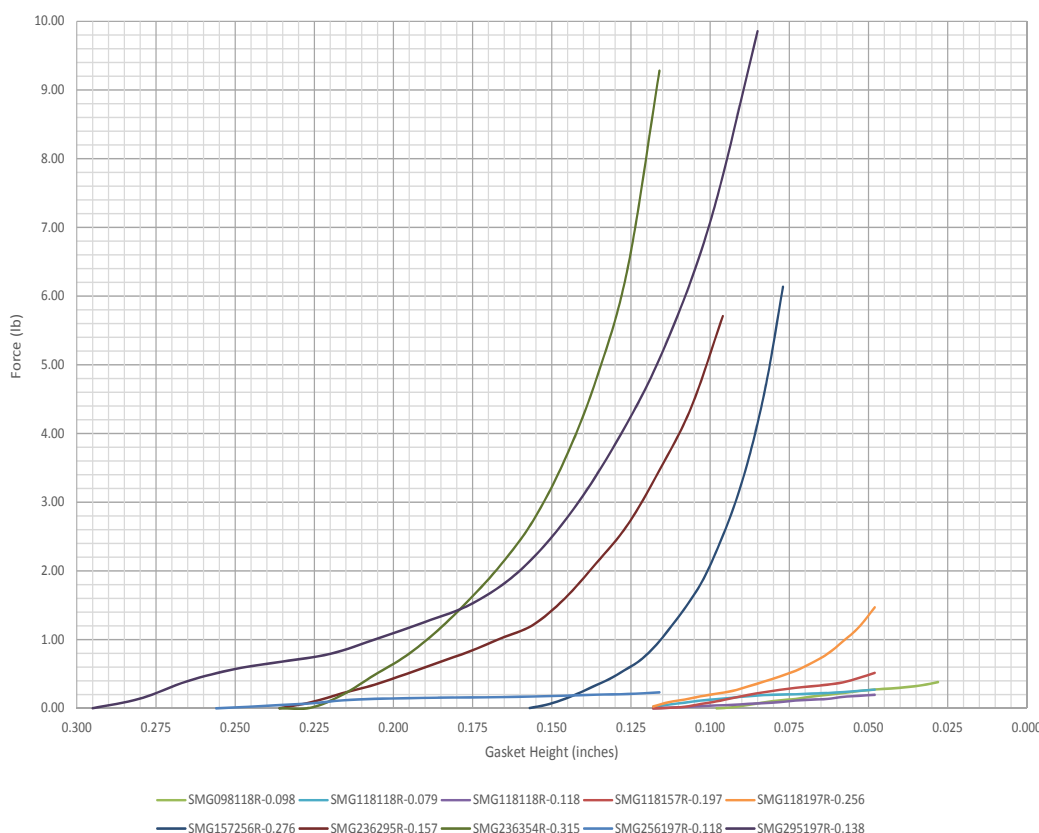
ISO 9001: 2015
CERTIFIED



Surface Mount Gaskets and Grounding Pads

Property	Method		Silicone Sponge	Polyurethane Foam
Outer Material	-		Polyimide coated Sn/Cu	Polyimide coated Sn/Cu
Color	-		Silver	Silver
Surface Resistance	ASTM D257		< 0.05 Ohm/in ²	< 0.05 Ohm/in ²
Hardness of Silicone	ASTM D2240		60 (Shore A)	20 (Shore C)
Deformation %	ASTM D5947	260°C, 30min	≤ 10%	≤ 10%
Resilience Ratio	ASTM D374	150°C, 100hrs, 20% compression	≥ 95%	≥ 85%
	ASTM D374	-40°C, 100hrs, 20% compression	≥ 95%	≥ 95%
	ASTM D374	85°C, 85% Rel. Humidity, 100hrs, 20% compression		
	ASTM D374	300 cycles, 20% compression		

Surface Mount Gasket - Force vs. Compression



Applications

- Mobile Electronics
- Computers
- Integrated Circuits

Benefits

- Low Cost
- Suitable for Automated Placement
- Tape & Reel Packaging
- Off-The-Shelf
- Reflow Capabilities
- Low Compression Requirements
- Resilient

Material

- Outer Wrap
- Polyimide coated Sn/Cu



**SURFACE
MOUNT GASKETS**

www.LeaderTechInc.com